

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1322isw#pbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.640905

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.006108 | 1000000 | 9530.265625 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.139415 | 975000 | 217528.171875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003432 | 24000 | 5354.92382812 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000043 | 300 | 67.0925750732 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000100 | 700 | 156.029251099 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.142990 | 1000000 | 223106.203125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.007167 | 1000000 | 11183.3417969 | | |
| | | External Plating Total: | | | | 0.007167 | 1000000 | 11183.3417969 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001144 | 1000000 | 1784.9744873 | | |
| | | Internal Plating Total: | | | | 0.001144 | 1000000 | 1784.9744873 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001493 | 750000 | 2329.51635742 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000498 | 250000 | 777.025634766 | | |
| Die Attach Total: | | | | 0.001991 | 1000000 | 3106.54223633 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.049522 | 103000 | 77268.8046875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.430316 | 895000 | 671418.8125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000962 | 2000 | 1501.00134277 | | |
| | | Encapsulation Total: | | | | 0.480800 | 1000000 | 750188.5625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000705 | 1000000 | 1100.00610352 | | |
| | | | | | TOTAL MASS (g) : | 0.640905 | | |